

L Number	Hits	Search Text	DB	Time stamp
3	324	(border\$1less with contact) and (stop or stopped or stopping or etch\$1stop or (etch adj stop))	USPAT	2004/09/16 11:31
4	206	((border\$1less with contact) and (stop or stopped or stopping or etch\$1stop or (etch adj stop))) and @ay<=1999	USPAT	2004/09/16 10:47
5	206	((border\$1less with contact) and (stop or stopped or stopping or etch\$1stop or (etch adj stop))) and @ay<=1999) and contact	USPAT	2004/09/16 10:49
6	32	("4318751" "4446476" "4519128" "4534824" "4549927" "4656497" "4733287" "4797373" "4808555" "4824793" "4876217" "4884123" "4939567" "4945069" "5003375" "5015594" "5064777" "5100823" "5106777" "5108938" "5112772" "5268330" "5275965" "5315142" "5362678" "5389559" "5395786" "5422294" "5457339" "5460987" "5482869" "5488010").PN.	USPAT	2004/09/16 10:56
7	5	("5316965" "5804862" "5880006" "5902127" "6051472").PN.	USPAT	2004/09/16 11:07
8	2	("5759867" "5935875").PN.	USPAT	2004/09/16 11:09
9	13	5840624.URPN.	USPAT	2004/09/16 11:21
10	458	border\$1less with contact	USPAT	2004/09/16 11:23
11	293	(border\$1less with contact) and @ay<=1999	USPAT	2004/09/16 11:24
12	87	((border\$1less with contact) and @ay<=1999) not (((border\$1less with contact) and (stop or stopped or stopping or etch\$1stop or (etch adj stop))) and @ay<=1999) and contact)	USPAT	2004/09/16 11:24
13	72358	(stop or stopped or stopping or etch\$1stop or (etch adj stop)) with (composite or two)	USPAT	2004/09/16 11:47
14	1076	(etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)	USPAT	2004/09/16 11:32
15	993	((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and semiconductor	USPAT	2004/09/16 11:32
16	855	((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and semiconductor) and contact	USPAT	2004/09/16 11:32
17	567	((((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and semiconductor) and contact) and @ay<=1999	USPAT	2004/09/16 11:33
18	253	(((((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and semiconductor) and contact) and @ay<=1999) and ((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (nitride or oxynitride or SiON or SiN or "Si.sub.3 N.sub.4"))	USPAT	2004/09/16 11:35
19	57	(((((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (composite or two)) and semiconductor) and contact) and @ay<=1999) and ((etch\$1stop\$4 or (etch\$3 adj stop\$4)) with (nitride or oxynitride or SiON or SiN or "Si.sub.3 N.sub.4"))) and ((stop or stopped or stopping or etch\$1stop or (etch adj stop)) with composite)	USPAT	2004/09/16 11:55

20	16	("3536547" "3926715" "4430153" "4440729" "4539392" "4600934" "4648179" "4671850" "4784721" "5055907" "5201987" "5229916" "5308442" "5369299" "5376586" "5670062").PN.	USPAT	2004/09/16 11:54
21	72	composite near4 etch\$3 near4 stop	USPAT	2004/09/16 15:05
22	42	(composite near4 etch\$3 near4 stop) and @ay<=1999	USPAT	2004/09/16 12:19
23	0	Qiao-Jiamin.in.	USPAT	2004/09/16 12:20
24	0	Tzur-Mira-Ben.in.	USPAT	2004/09/16 12:19
25	0	Gopalan-Prbhuram.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/16 12:20
26	0	Qiao-Jiamin.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2004/09/16 14:09
27	4003	((interconnect or interconnection) same (contact adj hole)	USPAT	2004/09/16 14:10
28	793	((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)	USPAT	2004/09/16 14:10
29	502	((((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)) and @ay<=1999	USPAT	2004/09/16 14:10
30	229	(((((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)) and @ay<=1999) and (polish or polishing or cmp or planariziation or planarize)	USPAT	2004/09/16 14:11
31	15	((((((interconnect or interconnection) same (contact adj hole)) and ((etch adj stop) or etch\$1stop or stopping or stopped)) and @ay<=1999) and (polish or polishing or cmp or planariziation or planarize)) and border\$1less	USPAT	2004/09/16 14:37
32	40	border\$1less and (((silicon adj oxide) or SiO) with ((silicon adj dioxide) or SiO?sub.2))	USPAT	2004/09/16 14:38
33	22	(border\$1less and (((silicon adj oxide) or SiO) with ((silicon adj dioxide) or SiO?sub.2))) and @ay<=1999	USPAT	2004/09/16 14:38
34	63	multi\$1layer near4 etch\$3 near4 stop	USPAT	2004/09/16
35	41	(multi\$1layer near4 etch\$3 near4 stop) and @ay<=1999	USPAT	15:02
36	84	(composite\$1 or compositing) near4 etch\$3 near4 stop\$4	USPAT	2004/09/16
37	50	((composite\$1 or compositing) near4 etch\$3 near4 stop\$4) and @ay<=1999	USPAT	15:05
38	8	((((composite\$1 or compositing) near4 etch\$3 near4 stop\$4) and @ay<=1999) not ((composite near4 etch\$3 near4 stop) and @ay<=1999))	USPAT	2004/09/16
39	201	border\$1less and (polishing or polish or cmp) and (etch\$1stop\$3 or (etch\$3 adj stop))	USPAT	15:06
40	123	(border\$1less and (polishing or polish or cmp) and (etch\$1stop\$3 or (etch\$3 adj stop))) and @ay<=1999	USPAT	2004/09/16 15:49
				2004/09/16 15:50
				2004/09/16 15:50

41	90	((border\$1less and (polishing or polish or cmp) and (etch\$1stop\$3 or (etch\$3 adj stop))) and @ay<=1999) and (doping or dopant or doped)	USPAT	2004/09/16 16:07
42	243	border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))	USPAT	2004/09/16 16:18
43	196	(border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and (phosphorous or P!)	USPAT	2004/09/16 16:09
44	131	((border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and (phosphorous or P!)) and @ay<=1999	USPAT	2004/09/16 16:10
45	60	(border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and phosphorous	USPAT	2004/09/16 16:09
46	45	((border\$1less and ((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2))) and phosphorous) and @ay<=1999	USPAT	2004/09/16 16:10
47	1620	((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous	USPAT	2004/09/16 16:18
48	1338	((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact	USPAT	2004/09/16 16:18
49	279	(((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact) and (weight or wt)	USPAT	2004/09/16 16:19
50	203	((((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact) and (weight or wt)) and @ay<=1999	USPAT	2004/09/16 16:19
51	72	((((doping or dopant or doped) with (oxide or dioxide or SiO or SiO?sub.2)) with phosphorous) and contact) and (weight or wt)) and @ay<=1999) and (stop or stopping)	USPAT	2004/09/16 16:34
52	166	PSG with weight	USPAT	2004/09/16 16:34
53	42	(PSG with weight) and @ay<=1990	USPAT	2004/09/16 16:34
54	13	5840624.URPN.	USPAT	2004/09/16 16:34
55	128	(PSG with weight) and @ay<=1999	USPAT	2004/09/16 16:35
-	317	((border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop)))	USPAT	2004/09/16 10:46
-	256	((border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop))) and @ay<=2000	USPAT	2004/09/15 19:00
-	241	((border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop))) and @ay<=2000) and (nitride or SiN or "Si.sub.3 N.sub.4" or oxy\$1nitride or SiON)	USPAT	2004/09/15 19:02
-	188	((border\$1less with contact) and (stop or stopping or etch\$1stop or (etch adj stop))) and @ay<=2000) and (nitride or SiN or "Si.sub.3 N.sub.4" or oxy\$1nitride or SiON)) and @ay<=1999	USPAT	2004/09/15 19:24
-	1	6156676.pn.	USPAT	2004/09/15 19:24
-	3	("3742183" "5543365" "5610104").PN.	USPAT	2004/09/15 19:27